

April 2000

FQPF9N50

500V N-Channel MOSFET

General Description

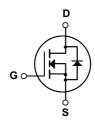
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

Features

- 5.3A, 500V, $R_{DS(on)}$ = 0.73 Ω @V_{GS} = 10 V Low gate charge (typical 28 nC)
- Low Crss (typical 20 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQPF9N50	Units
V _{DSS}	Drain-Source Voltage		500	V
I _D	Drain Current - Continuous (T _C = 25°	C)	5.3	А
	- Continuous (T _C = 100)°C)	3.4	А
I _{DM}	Drain Current - Pulsed	(Note 1)	21	А
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	360	mJ
I _{AR}	Avalanche Current	(Note 1)	5.3	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P _D	Power Dissipation (T _C = 25°C)		50	W
	- Derate above 25°C		0.4	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA		500			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 2	25°C	-	0.55		V/°C
I _{DSS}	Zees Cota Valta es Dusia Comuna	V _{DS} = 500 V, V _{GS} = 0 V				1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 400 V, T _C = 125°C				10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V		-		100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V		-		-100	nA
On Cha	aracteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.65 A		-	0.58	0.73	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 2.65 A (N	lote 4)		5.4		S
C _{iss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			1100 160 20	1450 210 30	pF pF pF
C _{rss}	Reverse Transfer Capacitance	1 – 1.0 MHZ		20	30	pF	
Switch	ing Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 250 V, I _D = 9.0 A,			25	60	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$			95	200	ns
t _{d(off)}	Turn-Off Delay Time			-	55	120	ns
t _f	Turn-Off Fall Time	(No	te 4, 5)	-	60	130	ns
Qg	Total Gate Charge	V _{DS} = 400 V, I _D = 9.0 A,		-	28	36	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		-	7.0		nC
Q _{gd}	Gate-Drain Charge	(No	te 4, 5)	-	12.5		nC
gu							
	Source Diode Characteristics a	nd Maximum Ratings					
	Source Diode Characteristics an					5.3	Α
Drain-S		ode Forward Current				5.3 21	A
Drain-S I _S	Maximum Continuous Drain-Source Dic	ode Forward Current Forward Current					
Drain-S	Maximum Continuous Drain-Source Did Maximum Pulsed Drain-Source Diode F	ode Forward Current				21	Α

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 23mH, I_{AS} = 5.3A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq 9.0A, di/dt \leq 200A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

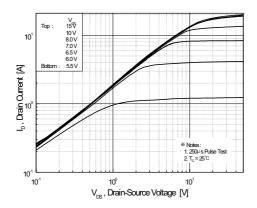


Figure 1. On-Region Characteristics

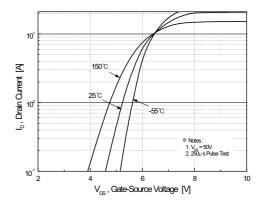


Figure 2. Transfer Characteristics

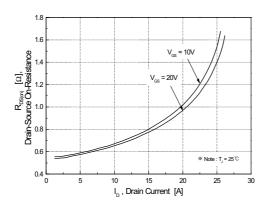


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

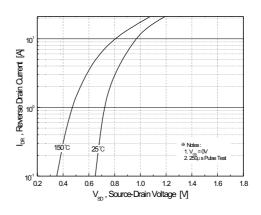


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

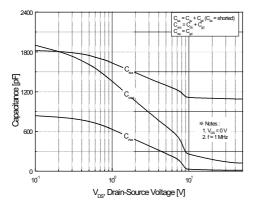


Figure 5. Capacitance Characteristics

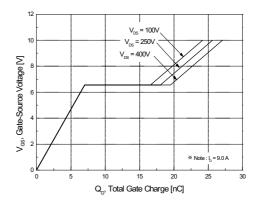


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

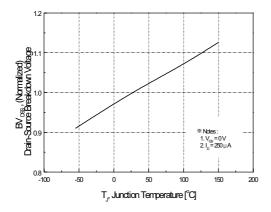
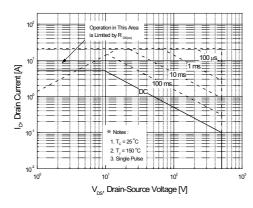


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



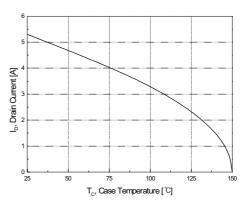


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

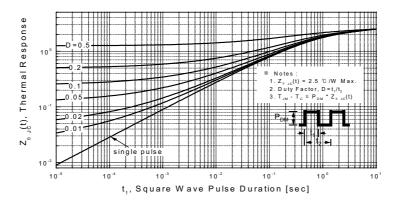
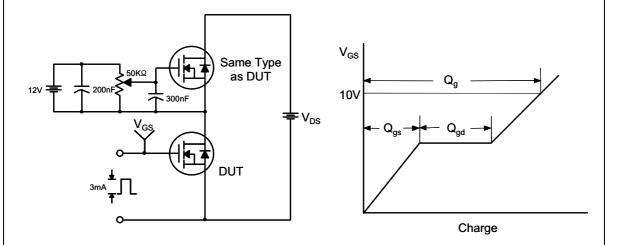


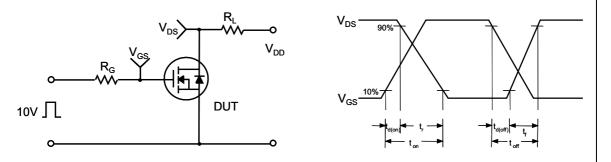
Figure 11. Transient Thermal Response Curve

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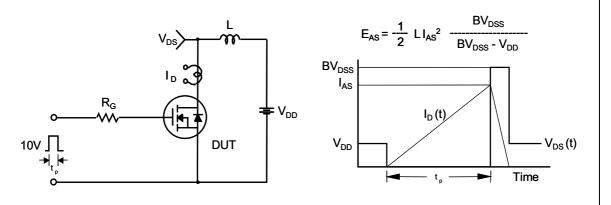
Gate Charge Test Circuit & Waveform



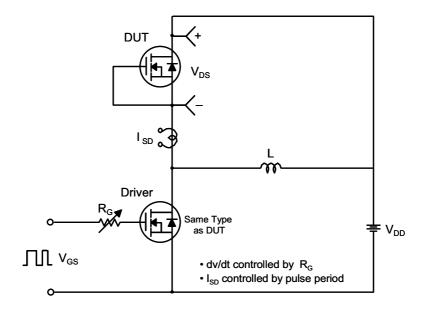
Resistive Switching Test Circuit & Waveforms

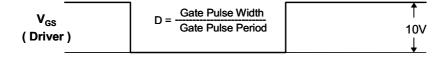


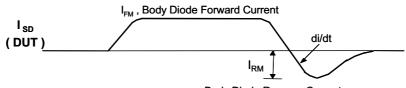
Unclamped Inductive Switching Test Circuit & Waveforms



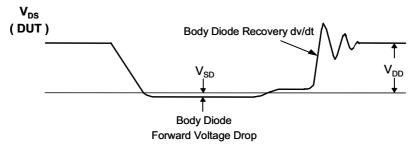
Peak Diode Recovery dv/dt Test Circuit & Waveforms



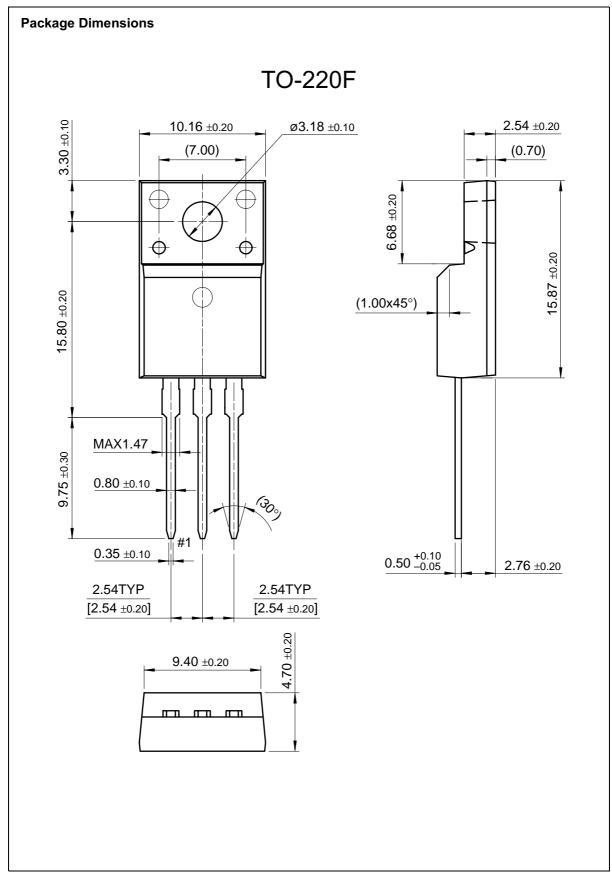




Body Diode Reverse Current



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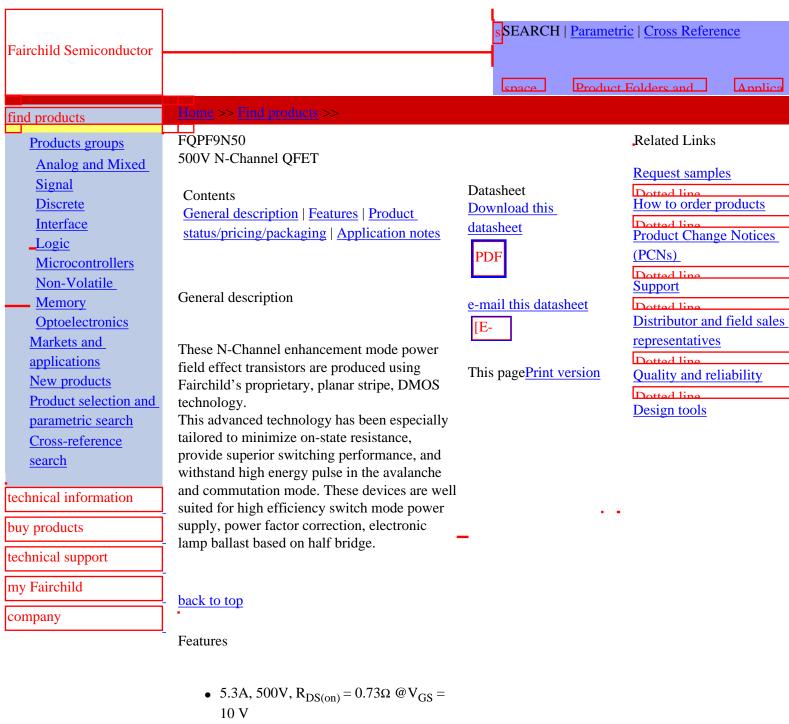
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Datasheet Identification	Product Status	Definition
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- Low gate charge (typical 28 nC)
- Low Crss (typical 20 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQPF9N50	Full Production	\$1.26	<u>TO-220F</u>	3	RAIL

Applica

FQPF9N50YDTU	Full Production	\$1.28	<u>TO-220F</u>	3	RAIL
FQPF9N50T	Full Production	\$1.28	<u>TO-220F</u>	3	RAIL

^{* 1,000} piece Budgetary Pricing

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Application notes

AN-4121: AN-4121 Design of Power Factor Correction Circuit Using FAN7527B (124 K) Jul 19, 2002

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